

MiniSKiiP<sup>®</sup> 3

3-phase bridge rectifier + brake chopper + 3-phase bridge inverter SKiiP 37NAB12T4V10

### Features

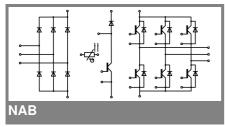
- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

#### **Typical Applications\***

- Inverter up to 36 kVA
- Typical motor power 22 kW

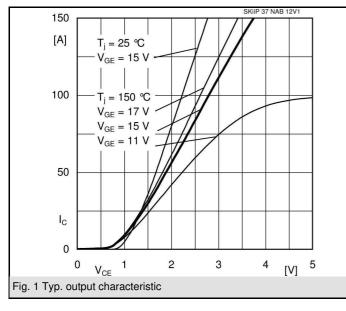
#### Remarks

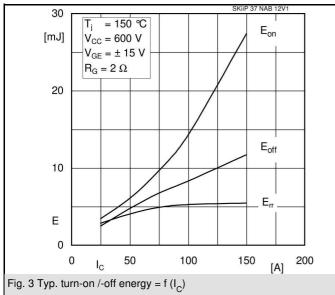
- V<sub>CEsat</sub> , V<sub>F</sub>= chip level value
- Case temp. limited to  $T_C = 125^{\circ}C$ max. (for baseplateless modules  $T_C = T_S$ )
- product rel. results valid for  $T_j \le 150$  (recomm.  $T_{op} = -40 \dots +150$ °C)

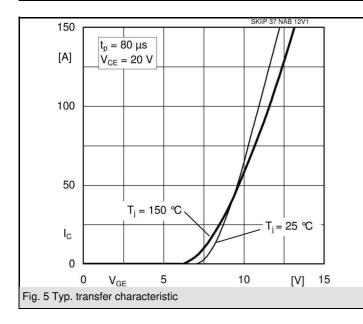


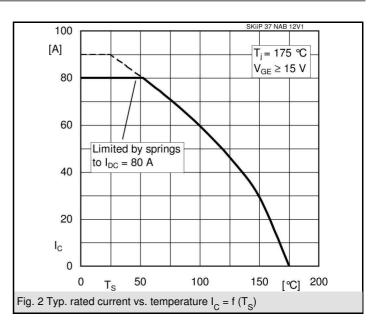
Absolute	T <sub>s</sub> = 25 °C, unless otherwise s	specified						
Symbol	Conditions	Values	Units					
IGBT - Inverter, Chopper								
V <sub>CES</sub>		1200	V					
I <sub>C</sub>	T <sub>s</sub> = 25 (70) °C	90 (73)	А					
I <sub>CRM</sub>		225	A					
V <sub>GES</sub>		± 20	V					
Т <sub>ј</sub>		- 40 + 175	°C					
Diode - Inverter, Chopper								
I <sub>F</sub>	T <sub>s</sub> = 25 (70) °C	82 (61)	А					
I <sub>FRM</sub>		225	А					
T <sub>j</sub>		- 40 + 175	°C					
Diode - Rectifier								
V <sub>RRM</sub>		1600	V					
I <sub>F</sub>	T <sub>s</sub> = 70 °C	67	А					
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180 °, T <sub>j</sub> = 25 °C	850	А					
i²t	t <sub>p</sub> = 10 ms, sin 180 °, T <sub>j</sub> = 25 °C	3600	A²s					
T <sub>j</sub>		- 40 + 150	°C					
Module								
I <sub>tRMS</sub>	per power terminal (20 A / spring)	80	А					
T <sub>stg</sub>		- 40 + 125	°C					
V <sub>isol</sub>	AC, 1 min.	2500	V					

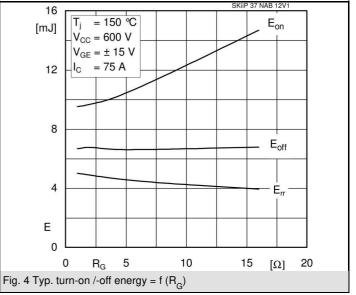
Character	ristics	T <sub>s</sub> = 25 °C	$s_s$ = 25 °C, unless otherwise specified						
Symbol	Conditions	min.	typ.	max.	Units				
IGBT - Inverter, Chopper									
V <sub>CEsat</sub>	I <sub>Cnom</sub> = 75 A, T <sub>j</sub> = 25 (150) °C		1,85 (2,25)	2,05 (2,45)	V				
V <sub>GE(th)</sub>	$V_{GE} = V_{CE}, I_C = 3 \text{ mA}$	5	5,8	6,5	V				
V <sub>CE(TO)</sub>	T <sub>j</sub> = 25 (150) °C		0,8 (0,7)	,	V				
r <sub>T</sub>	T <sub>j</sub> = 25 (150) °C		14 (21)	15 (22)	mΩ				
C <sub>ies</sub>	V <sub>CE</sub> = 25 V, V <sub>GE</sub> = 0 V, f = 1 MHz		4,4		nF				
C <sub>oes</sub>	$V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz$		0,29		nF				
C <sub>res</sub>	$V_{CE}$ = 25 V, $V_{GE}$ = 0 V, f = 1 MHz		0,24		nF				
R <sub>th(j-s)</sub>	per IGBT		0,58		K/W				
t <sub>d(on)</sub>	under following conditions		150		ns				
t <sub>r</sub> `´	$V_{CC}$ = 600 V, $V_{GE}$ = ± 15 V		35		ns				
t <sub>d(off)</sub>	I <sub>Cnom</sub> = 75 A, T <sub>j</sub> = 150°C		355		ns				
t <sub>f</sub>	$R_{Gon} = R_{Goff} = 2 \Omega$		60		ns				
E <sub>on</sub>	inductive load		9,7		mJ				
E <sub>off</sub>			6,8		mJ				
Diode - In	verter, Chopper								
$V_{F} = V_{EC}$	I <sub>Fnom</sub> = 75 A, T <sub>i</sub> = 25 (150) °C		2,2 (2,1)	2,5 (2,45)	V				
V <sub>(TO)</sub>	T <sub>i</sub> = 25 (150) °Ć		1,3 (0,9)	1,5 (1,1)	V				
r <sub>T</sub>	T <sub>j</sub> = 25 (150) °C		12 (16)	13 (18)	mΩ				
R <sub>th(j-s)</sub>	per diode		0,75		K/W				
I <sub>RRM</sub>	under following conditions		62		Α				
Q <sub>rr</sub>	I <sub>Enom</sub> = 75 A, V <sub>R</sub> = 600 V		12,6		μC				
E <sub>rr</sub>	V <sub>GE</sub> = 0 V, T <sub>i</sub> = 150 °C		4,9		mJ				
	di <sub>F</sub> /dt = 1940 A/µs								
Diode - Re	ectifier								
V <sub>F</sub>	I <sub>Fnom</sub> = 40 A, T <sub>i</sub> = 25 °C		1,1		V				
V <sub>(TO)</sub>	T <sub>i</sub> = 150 °C		0,8		V				
r <sub>T</sub>	T <sub>i</sub> = 150 °C		9		mΩ				
R <sub>th(j-s)</sub>	per diode		0,85		K/W				
	ure Sensor								
R <sub>ts</sub>	3 %, T <sub>r</sub> = 25 (100) °C		1000(1670)		Ω				
Mechanic		<u> </u>	. ,		I				
w			95		g				
	Mounting torque	2		2.5	Nm				
M <sub>s</sub>	Mounting torque	2		2,5					

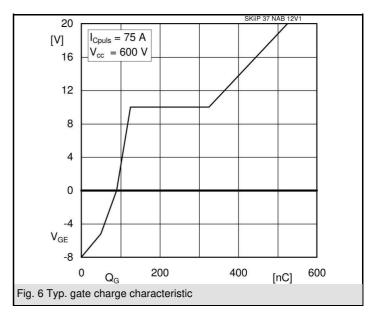


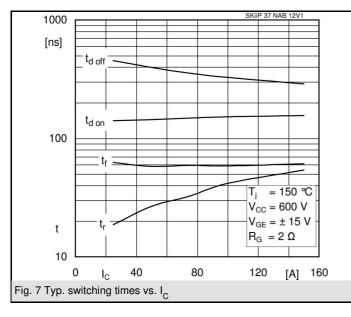


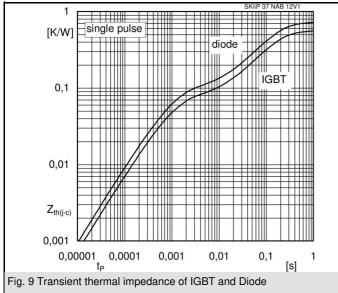


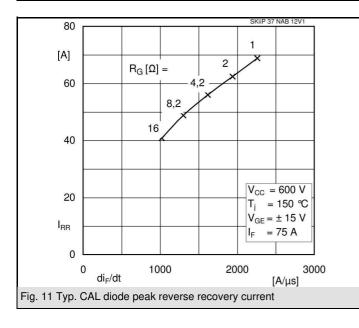


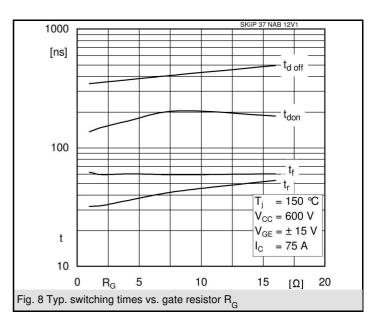


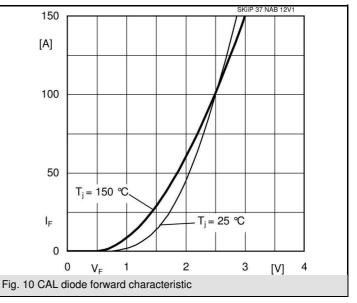


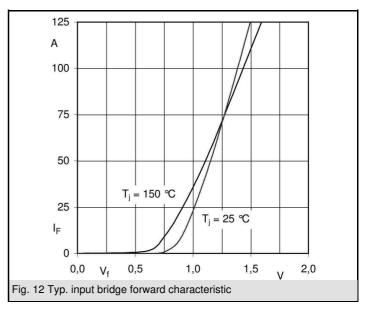


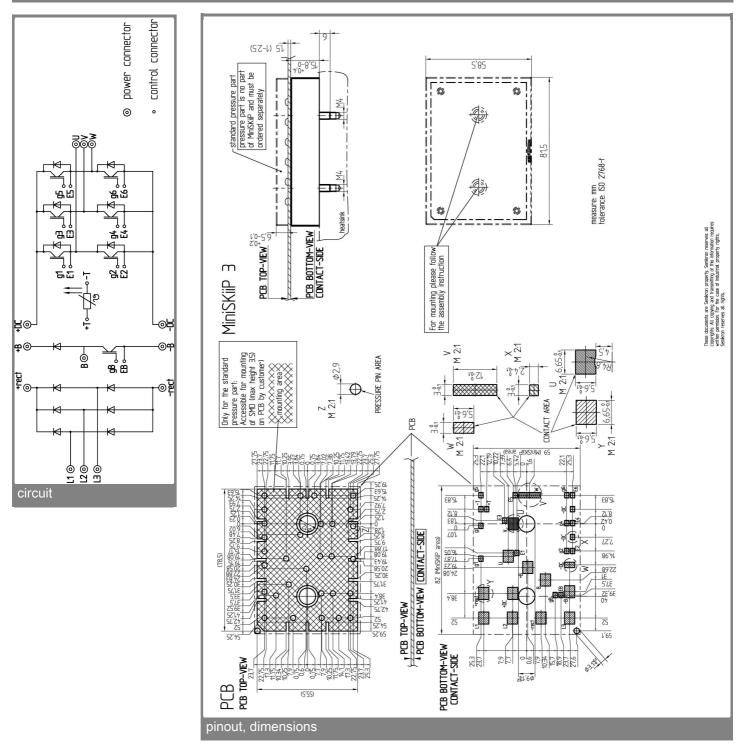












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.